L Number	Hits	Search Text	DB	Time stamp
1	261698	(alignment or tab or slot or pin) same (mask$4 or pattern$4 or resist or photoresist or photosensitiv$3 or photolithograph$5 or imag$4 or develop$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:23
2	47893	((alignment or tab or slot or pin) same (mask$4 or pattern$4 or resist or photoresist or photosensitiv$3 or photolithograph$5 or imag$4 or develop$4)) same (etch$5 or remov$4 or laser or ablat$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:24
3	1012	(((alignment or tab or slot or pin) same (mask$4 or pattern$4 or resist or photoresist or photosensitiv$3 or photolithograph$5 or imag$4 or develop$4)) same (etch$5 or remov$4 or laser or ablat$4)) and 216/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:24
4	31	((((alignment or tab or slot or pin) same (mask$4 or pattern$4 or resist or photoresist or photosensitiv$3 or photolithograph$5 or imag$4 or develop$4)) same (etch$5 or remov$4 or laser or ablat$4)) and 216/$.ccls.) and 216/17.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:40
5	37567	(metal$4 or copper or cu or conducting or conductive or trace or metallization) near4 (mask$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:46
6	3946	((metal$4 or copper or cu or conducting or conductive or trace or metallization) near4 (mask$4)) and (((alignment or tab or slot or pin) same (mask$4 or pattern$4 or resist or photoresist or photosensitiv$3 or photolithograph$5 or imag$4 or develop$4)) same (etch$5 or remov$4 or laser or ablat$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:43
7	301	((metal$4 or copper or cu or conducting or conductive or trace or metallization) near4 (mask$4)) and ((((alignment or tab or slot or pin) same (mask$4 or pattern$4 or resist or photoresist or photosensitiv$3 or photolithograph$5 or imag$4 or develop$4)) same (etch$5 or remov$4 or laser or ablat$4)) and 216/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:43
8	7	((metal$4 or copper or cu or conducting or conductive or trace or metallization) near4 (mask$4)) and (((((alignment or tab or slot or pin) same (mask$4 or pattern$4 or resist or photoresist or photosensitiv$3 or photolithograph$5 or imag$4 or develop$4)) same (etch$5 or remov$4 or laser or ablat$4)) and 216/$.ccls.) and 216/17.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:43
9	11851	(metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:56
10	1196	((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) and (((alignment or tab or slot or pin) same (mask$4 or pattern$4 or resist or photoresist or photosensitiv$3 or photolithograph$5 or imag$4 or develop$4)) same (etch$5 or remov$4 or laser or ablat$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:47
11	588	((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) and 216/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:47
12	154	((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) and 219/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:47

13	33	(((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) and 216/$.ccls.) and (((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) and 219/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:54
14	8	((((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) and 216/$.ccls.) and (((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) and 219/$.ccls.)) and alignment	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:54
15	197	((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) with (alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:56
16	25	(((metal$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask$4)) with (alignment)) with etch$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:57